

CM0805D900R-10

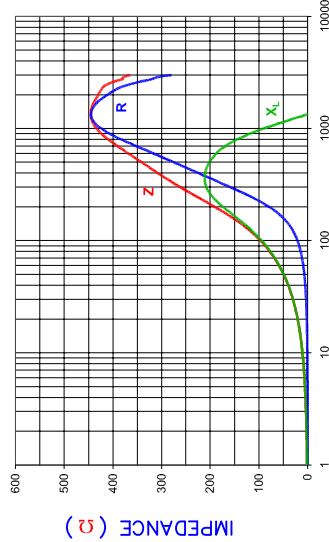
UNCONTROLLED
DOCUMENT

PHYSICAL DIMENSIONS:

A	2.00	[.079]	+ 0.20	[.008]
B	1.20	[.047]	+ 0.20	[.008]
C	1.20	[.047]	+ 0.20	[.008]
D	0.15	[.006]	+ 0.10	[.004]

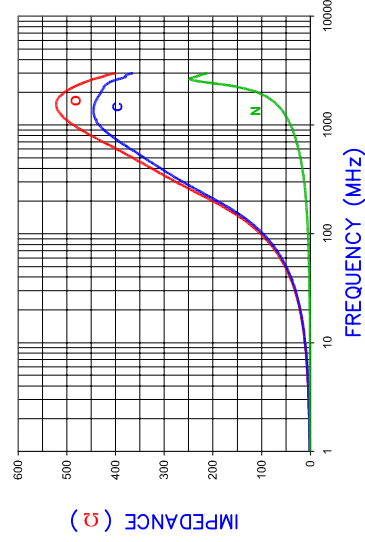
T1	0.55	[.022]	+ 0.10	[.004]
T2	0.46	[.018]	+ 0.10	[.004]

Z, R, XL vs. FREQUENCY



FREQUENCY (MHz)

Z vs. FREQUENCY (C,N,O)



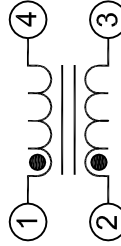
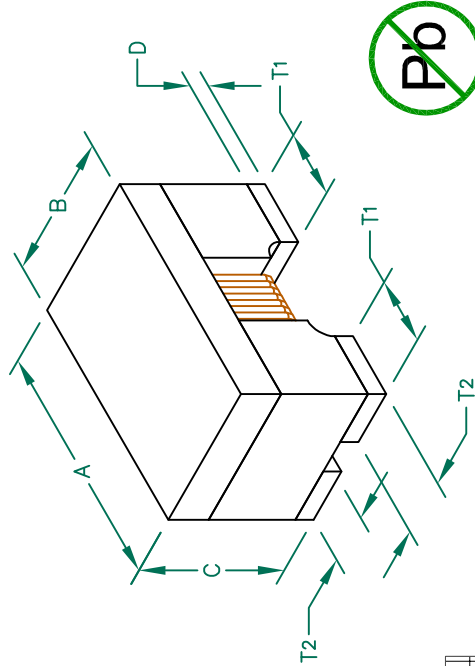
FREQUENCY (MHz)

Normal

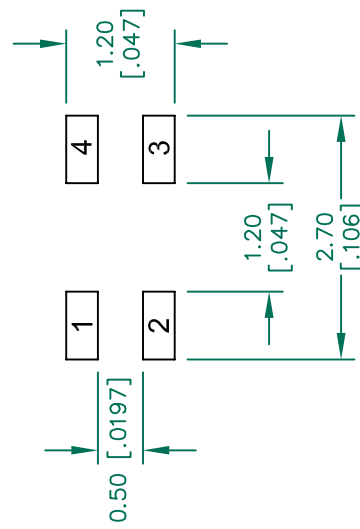
Common

Open

AGILENT E4991A RF Impedance/Material Analyzer
HP 16194A Test Fixture. TEST REF. 5788



LAND PATTERNS FOR REFLOW SOLDERING

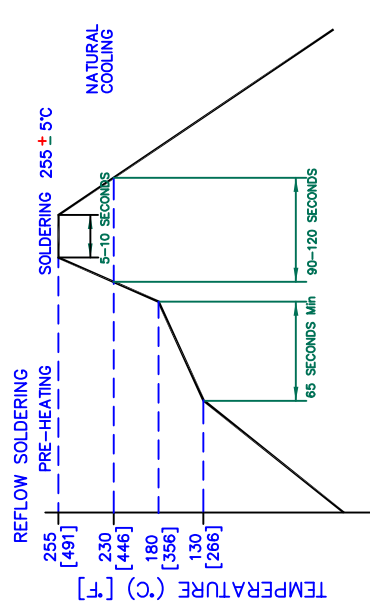


Electrical Characteristics		Nominal	Min	Max
Common Mode Impedance @ 100MHz	(Ω)	90	67.5	112.5
	DCR	(Ω)	—	0.3
Rated Current		(mA)	—	400

NOTES: UNLESS OTHERWISE SPECIFIED

1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, EMBOSSED PLASTIC TAPE 2,000 PCS/REEL.
2. TERMINATION FINISH 100% MATTE TIN.
3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
4. OPERATING TEMP. RANGE: -40°C~+125°C. (INCLUDING SELF-HEATING)

RECOMMENDED SOLDERING CONDITIONS



DIMENSIONS ARE IN mm [INCHES].

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E	ADD OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13	QU	PROJECT/PART NUMBER: CM0805D900R-10		REV E	PART TYPE: CM CHOKE
D	UPDATE SOLDERING TEMPERATURE	04/01/11	WEI	DATE: 08/11/06		SHEET: 2 of 2	
C	UPDATE COMPANY LOGO	04/28/09	JRK	SCALE: 1:1		DRAWN BY: JRK	
B	UPDATE COMPANY LOGO	05/14/07	JRK	DATE: 08/11/06		SHEET: 2 of 2	
A	ORIGINAL DRAFT	08/11/06	JRK	DATE: 08/11/06		SHEET: 2 of 2	
REV	DESCRIPTION	DATE	INT	DATE: 08/11/06		SHEET: 2 of 2	